

On page 16, please amend lines 13-18 as follows:

G²
--The area of the EPD window 104 is made much wider than the actual pattern area of the lower plate 70 so that reaction gas generated during etching is increased to make the detection of gas easier. The EPD window 104 is not limited to the area as shown in Fig. 12, but can be formed on a non-display part 110 of the lower plate 70 or between the pads 50 and 90 at a pad part 112, as shown in Fig. 13.--

On page 14, please amend lines 5-9 as follows:

G³
--Improvement can be made when defining the holes 56 or 94. In the above embodiment, the organic protective film 78 and the gate insulating film 74 are etched to expose the lower glass substrate 72. However, during the actual etching process, a portion of the lower glass substrate 72 may be etched as well.--